

SMD Power Inductor

TMPC0315HV-SERIES(G)

1. Features

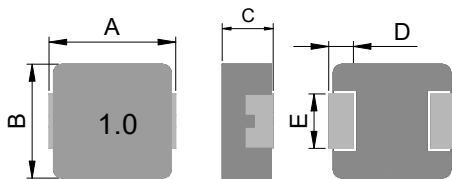
1. Carbonyl Powder.
2. Compact design.
3. High current , low DCR , high efficiency.
4. Very low acoustic noise and very low leakage flux noise.
5. High reliability.
6. 100% Lead(Pb)-Free and RoHS compliant.
7. High reliability -Reliability test complied to AEC-Q200.
8. Operating temperature -55~+125°C(Including self - temperature rise)



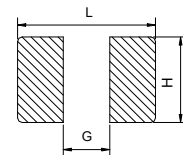
2. Applications

Note PC power system , incl. IMVP-6
DC/DC converter .

3. Dimensions



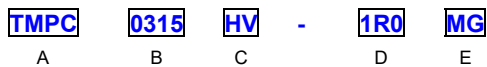
Recommend PC Board Pattern



Series	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
TMPC0315HV	3.5±0.3	3.2±0.2	1.3±0.2	0.7±0.2	1.2±0.2

L(mm)	G(mm)	H(mm)
4.1	1.9	1.45

4. Part Numbering



- A: Series
- B: Dimension
- C: Type
- D: Inductance
- E: Inductance Tolerance
- BxC
- Carbonyl Powder.
- 1R0=1.0uH
- M=±20%, One-way Black marking

Note: 1. The above PCB layout reference only.
2. Recommend solder paste thickness at 0.12mm and above.

5. Specification

Part Number	Inductance L0 (uH)±20%	I rms (A)	I sat (A)	DCR(mΩ) Typ.@25°C	DCR(mΩ) Max.@25°C
TMPC0315HV-R22MG	0.22	7.0	10.8	14	17
TMPC0315HV-R47MG	0.47	5.5	8.0	23.3	28
TMPC0315HV-R56MG	0.56	5.0	7.2	28	33
TMPC0315HV-R68MG	0.68	4.5	6.5	34	42
TMPC0315HV-1R0MG	1.00	3.6	5.8	41	50
TMPC0315HV-1R5MG	1.50	3.4	4.0	64	77
TMPC0315HV-2R2MG	2.20	3.2	3.8	82	98
TMPC0315HV-3R3MG	3.30	2.5	3.2	170	205
TMPC0315HV-4R7MG	4.70	1.9	2.8	220	264
TMPC0315HV-5R6MG	5.60	1.7	2.3	265	318
TMPC0315HV-6R8MG	6.80	1.5	2.0	290	348
TMPC0315HV-8R2MG	8.20	1.3	1.8	390	468
TMPC0315HV-100MG	10.0	1.2	1.6	435	522

1. Test frequency : Ls : 100KHz /1.0V.
2. All test data referenced to 25°C ambient.
3. Testing Instrument(or equ) : L: HP4284A,CH11025,CH3302,CH1320,CH1320S LCR METER / Rdc:CH16502,Agilent33420A MICRO OHMMETER.
4. Heat Rated Current (I rms) will cause the coil temperature rise approximately ΔT of 40°C
5. Saturation Current (I sat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions. Circuit design, component, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. Special inquiries besides the above common used types can be met on your requirement.

6. Typical Performance Curves

